0.8A, 200V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- AEC-Q101 gualified
- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

MECHANICAL DATA

- Case: SOD-123W
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	0.8	А	
V _{RRM}	200 - 1000	V	
I _{FSM}	20	А	
T _{J MAX}	150 °C		
Package	SOD-123W		
Configuration	Single die		





SOD-123W



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	HSD LWH	HSG LWH	HSJ LWH	HSK LWH	HSM LWH	UNIT
Marking code on the device		HSDLW	HSGLW	HSJLW	HSKLW	HSMLW	
Repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	560	700	V
Forward current	I _F			0.8			Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	20			A		
Junction temperature	TJ	- 55 to +150		°C			
Storage temperature	T _{STG}	- 55 to +150		°C			





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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	R _{θJL}	34	°C/W	
Junction-to-ambient thermal resistance	R _{θJA}	86	°C/W	
Junction-to-case thermal resistance	R _{eJC}	35	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
	HSDLWH	$I_F = 0.4A, T_J = 25^{\circ}C$		0.81	0.97	V
		I _F = 0.8A, T _J = 25°C		0.86	1.00	V
		$I_F = 0.4A, T_J = 125^{\circ}C$		0.66	0.79	V
		$I_F = 0.8A, T_J = 125^{\circ}C$		0.73	0.83	V
		$I_F = 0.4A, T_J = 25^{\circ}C$		0.84	1.01	V
(1)		$I_F = 0.8A, T_J = 25^{\circ}C$		0.91	1.30	V
Forward voltage ⁽¹⁾	HSGLWH	$I_F = 0.4A, T_J = 125^{\circ}C$	V _F	0.70	0.83	V
		I _F = 0.8A, T _J = 125°C		0.77	1.05	V
	HSJLWH HSKLWH HSMLWH	$I_F = 0.4A, T_J = 25^{\circ}C$		1.17	1.40	V
		I _F = 0.8A, T _J = 25°C		1.31	1.70	V
		I _F = 0.4A, T _J = 125°C		0.93	1.12	V
		I _F = 0.8A, T _J = 125°C		1.09	1.30	V
- (2)	1	T _J = 25°C		-	1	μA
Reverse current @ rated $V_R^{(2)}$		T _J = 125°C	I _R	-	150	μA
	HSDLWH			17	-	pF
	HSGLWH	1MHz, V _R = 4.0V	CJ	14	-	pF
Junction capacitance	HSJLWH					
	HSKLWH			5	-	pF
	HSMLWH					
Reverse recovery time	HSDLWH		t _{rr}	_	50	
	HSGLWH	I _F = 0.5A , I _R = 1.0A		-	50	ns
	HSJLWH					
	HSKLWH	$I_{rr} = 0.25A$		-	75	ns
	HSMLWH					

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
HSxLWH	SOD-123W	10,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 200V(HSDLWH) to 1000V(HSMLWH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

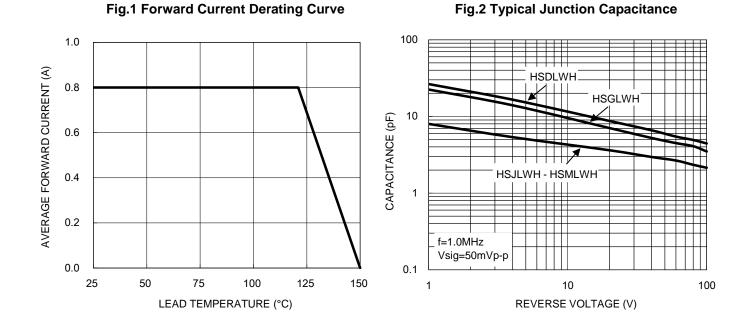


Fig.3 Typical Reverse Characteristics

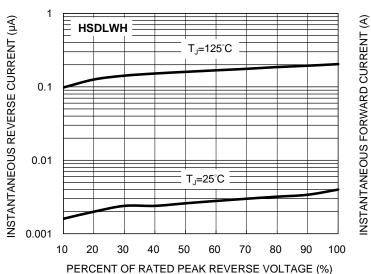
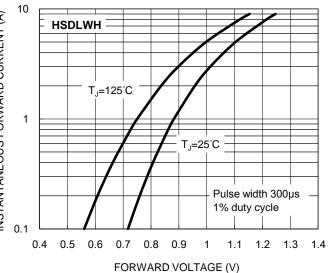


Fig.4 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

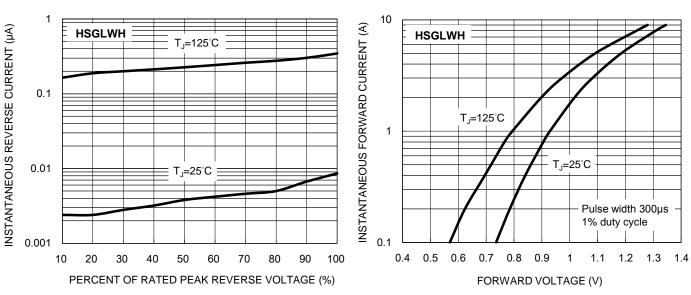


Fig.5 Typical Reverse Characteristics

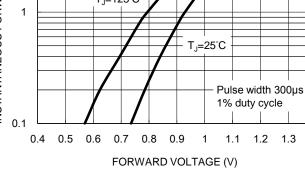


Fig.6 Typical Forward Characteristics

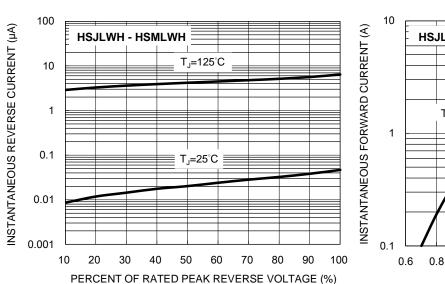
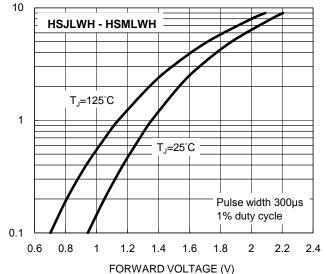


Fig.7 Typical Reverse Characteristics

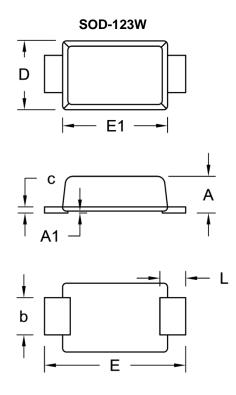
Fig.8 Typical Forward Characteristics



HSDLWH – HSMLWH

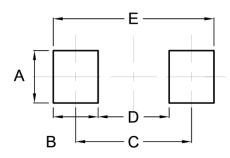
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PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)		
	Min.	Max.	Min.	Max.	
A	0.90	1.02	0.035	0.040	
A1	0.00	0.10	0.000	0.004	
b	0.90	1.05	0.035	0.041	
с	0.10	0.22	0.004	0.009	
D	1.70	1.90	0.067	0.075	
E	3.60	3.80	0.142	0.150	
E1	2.60	2.90	0.102	0.114	
L	0.50	0.85	0.020	0.033	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

MARKING DIAGRAM



P/N = Marking Code

YW = Date Code

F = Factory Code



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